VLSI DESIGN FLOW: RTL TO GDS

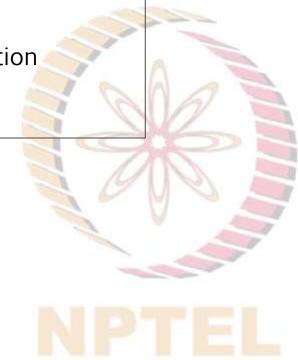
Lecture 34
Built-in Self-test (BIST)



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Lecture Plan

- Distinguishing Features
- Architecture
- Random Test Pattern Generation
- Test Response Analyser



Built-in Self Test (BIST)

Drawbacks of ATE-based testing:

- Cost of testing high
 - > ATE cost
 - > Voluminous test data: increase test time
- Can be done only in production test environment
 - ➤ Lacks capability of field testing
- At-speed test difficult
 - Probe's inductance/capacitance bottleneck

BIST as a solution:

- Test-oriented additional hardware and software features inside a given IC
- Allows IC to test their own operation
- Reducing dependence on an external ATE for testing
 - > Repair in the field possible

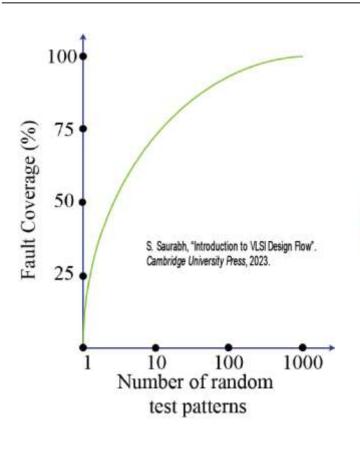


Built-in Self Test (BIST): Distinguishing Features

- 1. Contains *Pseudo-random pattern generator* inside the chip
 - > Provides test vectors dynamically
 - > Avoids storing voluminous test vectors
- 2. Performs *signature analysis* for detecting failures
 - > Does not perform comparison of exact response
 - > Avoids storing voluminous expected response inside the chip

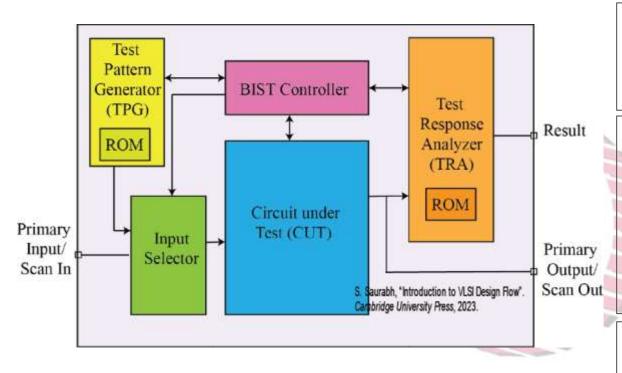


Testability: Fault Coverage vs. Random Test Pattern Count



- Stuck-At Fault coverage rises to 100% logarithmically
- Reaching 90% coverage is easy using random patterns

BIST: Architecture



Test Pattern Generator (TPG)

- > Generates pattern for testing
- > Can contain ROM

Test Response Analyzer (TRA)

- ➤ Generates signature for the test response and compare
- > ROM stores golden signature
- > Compares test signature with the golden signature

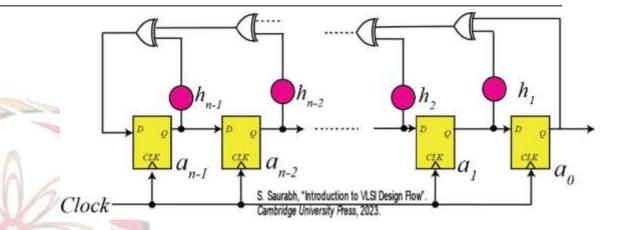
Test Controller

- Controls all the operations of BIST
- Strategy for overall test control is most difficult part of BIST

BIST: Test Pattern Generator

Pseudo-Random Pattern Generator

- ➤ Linear Feedback Shift Register (LFSR)
- ➤ Repeatable
- ➤ Small hardware can produce large number of "random" test patterns
- We can tap the output of any flip-flop to provide feedback.
- If we tap the output a_i of the i-th flip-flop, then h_i is taken as 1, else it is taken as 0.

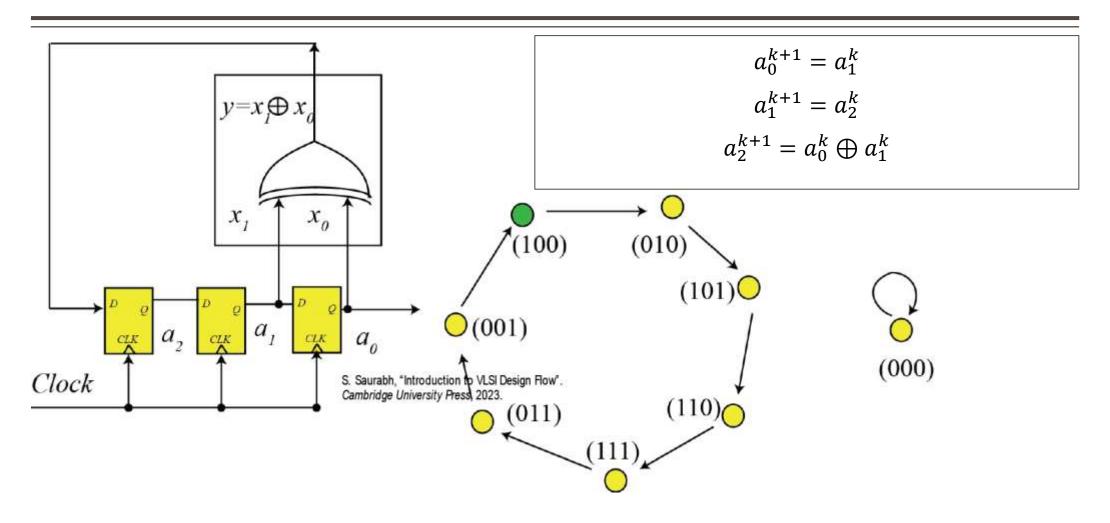


$$a_0^{k+1} = a_1^k$$

$$a_1^{k+1} = a_2^k$$
....
$$a_{n-2}^{k+1} = a_{n-1}^k$$

$$a_{n-1}^{k+1} = a_0^k \oplus h_1 a_1^k \oplus h_2 a_2^k \oplus ... \oplus h_{n-1} a_{n-1}^k$$

Pattern Generator: Illustration



Pattern Generator: Considerations

LFSR

- > Test patterns generated by an LFSR have most of the properties of random numbers
- > Desirable to have long sequence so that good fault coverage is achieved
- Some faults may be not covered by random pattern generator
 - > Use ATPG to get deterministic test-vector and put those test-vectors in ROM
 - > Helps achieve high fault coverage with small number of test vectors

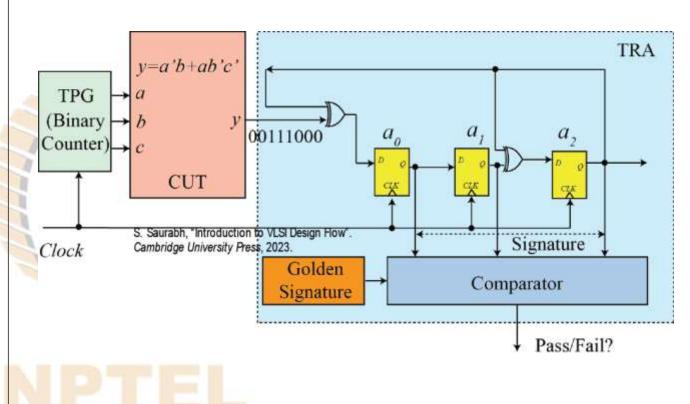


BIST: Test Response Analyzer (1)

- No. of test patterns can be large (e.g. 1 million) and there can be many outputs (e.g. 100)
 - > Too voluminous data to store in ROM (100 million bits)
- Compaction: method of reducing the number of bits in the circuit response
- Signature: a statistical property of a circuit, usually a number computed for a circuit from its responses
- Signature Analysis: signature of a good circuit ("golden signature") compared with the signature of a "potentially" faulty circuit ("test signature")
 - > If "golden signature" matches "test signature" then the circuit is assumed to be good, else faulty
 - > Desirable: signature of a good circuit and faulty circuits are different
- Aliasing: During testing, it is possible that the signature of "good" circuit and "faulty" circuit match
 - > Due to information loss during compaction

BIST: Test Response Analyzer

- Techniques to compute Signature
 - > Ones Counting: count number of ones across all circuit responses
 - □ Different permutations can yield same signature
 - ➤ Modular LFSR: Extra XOR gate at the input
 - ☐ Single Input Signature Register (SISR)
 - Need to start with a seed value



Built-in Self Test (BIST)

Advantages

- Lower cost of test, since the need for external electrical testing using an ATE will be reduced
- No need to store test patterns
- At-speed test can be done
- Capability to perform tests outside the production electrical testing environment

Disadvantages

- Additional silicon area
 - Yield and Reliability decrease
- Performance loss
 - > Extra delays
- Additional pin (and possibly bigger package size) requirements

References

- M. Bushnell and V. Agrawal, "Essentials of electronic testing for digital, memory and mixedsignal VLSI circuits", Springer Science & Business Media, 2004.
- S. Saurabh, "Introduction to VLSI Design Flow". Cambridge: Cambridge University Press, 2023.

